L Number	Hits	Search Text	DB	Time stamp
-	21	"non-key" and semiconductor	USPAT;	2004/04/27
		-	US-PGPUB;	11:33
			EPO; JPO;	
			DERWENT	
- 1	12	5,978,807	USPAT;	2004/04/27
		• • • • • • • • • • • • • • • • • • • •	US-PGPUB;	14:36
			EPO; JPO;	
			DERWENT	
_	2	"common tool set capacity"	USPAT;	2004/04/27
	_	• • • •	US-PGPUB;	14:36
			EPO; JPO;	
			DERWENT	
-	1	"common tool set" and semiconductor	USPAT;	2004/04/27
			US-PGPUB;	14:37
			EPO; JPO;	<u>:</u>
			DERWENT	
_	605	capacity and overall and wafer and	USPAT;	2004/04/27
	_	semiconductor and calculating	US-PGPUB;	14:37
			EPO; JPO;	
			DERWENT	,
_	5	(capacity and overall and wafer and	USPAT;	2004/04/27
		semiconductor and calculating) and	US-PGPUB;	14:50
		"overall capacity" and dividing	EPO; JPO;	- X
			DERWENT	
-	2	"capacity consumption factor"	USPAT;	2004/04/27
	_		US-PGPUB;	14:51
			EPO; JPO;	
			DERWENT	
_	15	"5946212"	USPAT;	2004/04/27
			US-PGPUB;	14:53
			EPO; JPO;	
			DERWENT	1
_	1		USPAT	2004/04/27
				14:51
-	1	,	USPAT	2004/04/27
				14:51
-	1		USPAT	2004/04/27
1				14:52
_ ]	20	"capacity planning" and technologies and	USPAT;	2004/04/27
		"tool sets"	US-PGPUB;	15:21
	!		EPO; JPO;	1
			DERWENT	
-	26	"technology based" and "design based" and	USPAT;	2004/04/27
	1	semiconductor	US-PGPUB;	15:30
	'		EPO; JPO;	
			DERWENT	
<b>-</b>	632	fabricator and technology and design	USPAT;	2004/04/27
		·	US-PGPUB;	15:30
			EPO; JPO;	<u> </u>
			DERWENT	
_	11	(fabricator and technology and design)	USPAT;	2004/04/27
		and organizing	US-PGPUB;	15:31
			EPO; JPO;	
			DERWENT	· ·
-	210	(fabricator and technology and design)	USPAT;	2004/04/27
		and wafer	US-PGPUB;	15:31
			EPO; JPO;	
			DERWENT	